Connector for ExpressCard™

SCBA/SCBB Series
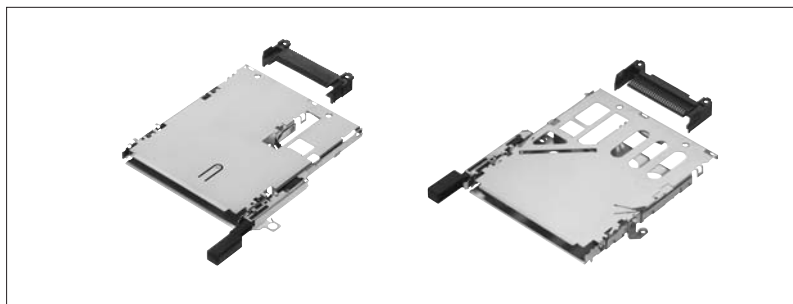
Compact low-profile and power-saving structure conforms to PCMCIA Unified Standard.

Features

- Simple structure contributes to compact and light weight body.
- Eject knob can be applied to the left or right side.
- Also available in stand-off.
- Pin header (SCBA) is provided with an adsorption area allowing automatic mounting.

Applications

- For set top boxes, printers, digital still cameras, car navigation systems, personal digital assistants, PCs and AV equipment

■Typical Specifications

Items		Specifications
Structure	**Applicable media**	ExpressCard™34/54 which confirm to ExpressCard™ standard
	Mounting method	Surface mounting type
	Mounting system	Standard mount / Reverse mount
	Contact pitch	1mm
	Number of contacts	26 pins
Performance	**Operating temperature range**	−20℃ to ＋70℃
	Voltage proof	500V AC 1minute
	Insulation resistance（Initial）	1,000MΩ min.
	Contact resistance（Initial）	120mΩ max.
	Insertion and removal cycle	5,000cycles

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■Product Line

Media ejection structure	Mounting system	Stand-off （mm）	Position of knob	Product No.	Minimum packing unit （pcs.）※	Drawing No.
2 step lever ejection type	Standard mount	1.6	Right	Pin header SCBA7M0100	550	1
				Ejector SCBB7B0100	120	
	Reverse mount	0		Pin header SCBA2M0100	550	2
				Ejector SCBB2B0100	120	
		1.75		Pin header SCBA8M0100	550	3
				Ejector SCBB8B0100	120	

Notes
1. ※ It is requested that the order placed be an integer multiple of the minimum order units.
2. The pin headers and the ejectors are supplied as separate parts. When using them, solder a pin header to a printed circuit board, assemble an ejector to the pin header and screw it.
3. For export packing, please consult us.

■Dimensions
Standard mount   Unit:mm

No.	Style	PC board mounting hole dimensions （Viewed from the mounting face side）
1	**Stand-off 1.6mm**	

■**Dimensions**
Reverse mount   Unit:mm

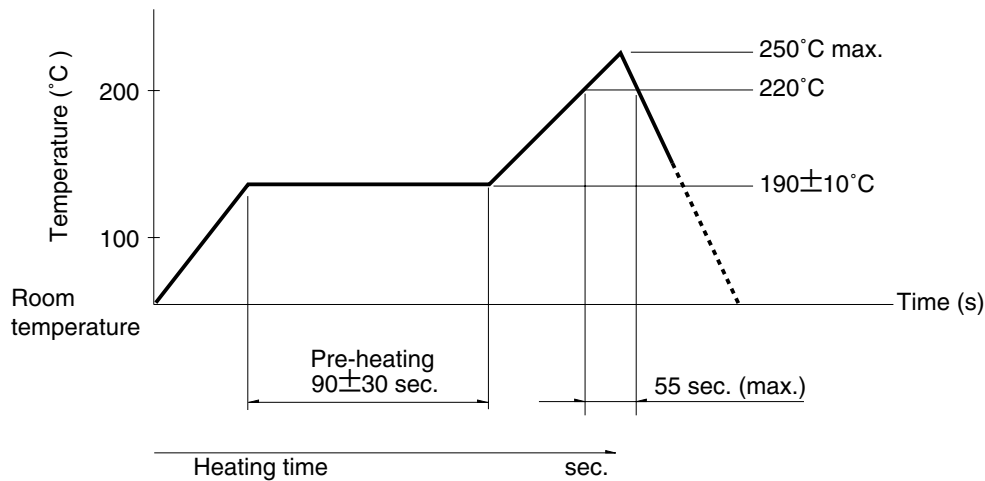| No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
2	**Stand-off 0mm** 	
3	**Stand-off 1.75mm** 	

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Soldering Conditions

Example of Reflow Soldering Condition（Reference）

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA（K）or CC（T）.
3. Temperature profile.

Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. When soldering, do not use water soluble flux because this may corrode the product.
3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.

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